

**Integrated chip package structure using metal substrate and method of  
manufacturing the same**

Appl. No. : 10/055,560 Confirmation No. 6103  
Applicant : Mou-Shiung Lin,  
Jin-Yuan Lee,  
Ching-Cheng Huang  
Filed : January 22, 2002  
TC/A.U. : 2813  
Examiner : Mitchell, James M  
Docket No. : MEGP0009USA  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

5 **RESPONSE TO NON-FINAL OFFICE ACTION**

Sir:

In response to the Non-Final Office Action mailed Mar. 19, 2008, please amend the above-identified application and consider the remarks as follows:

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 9 of this paper.